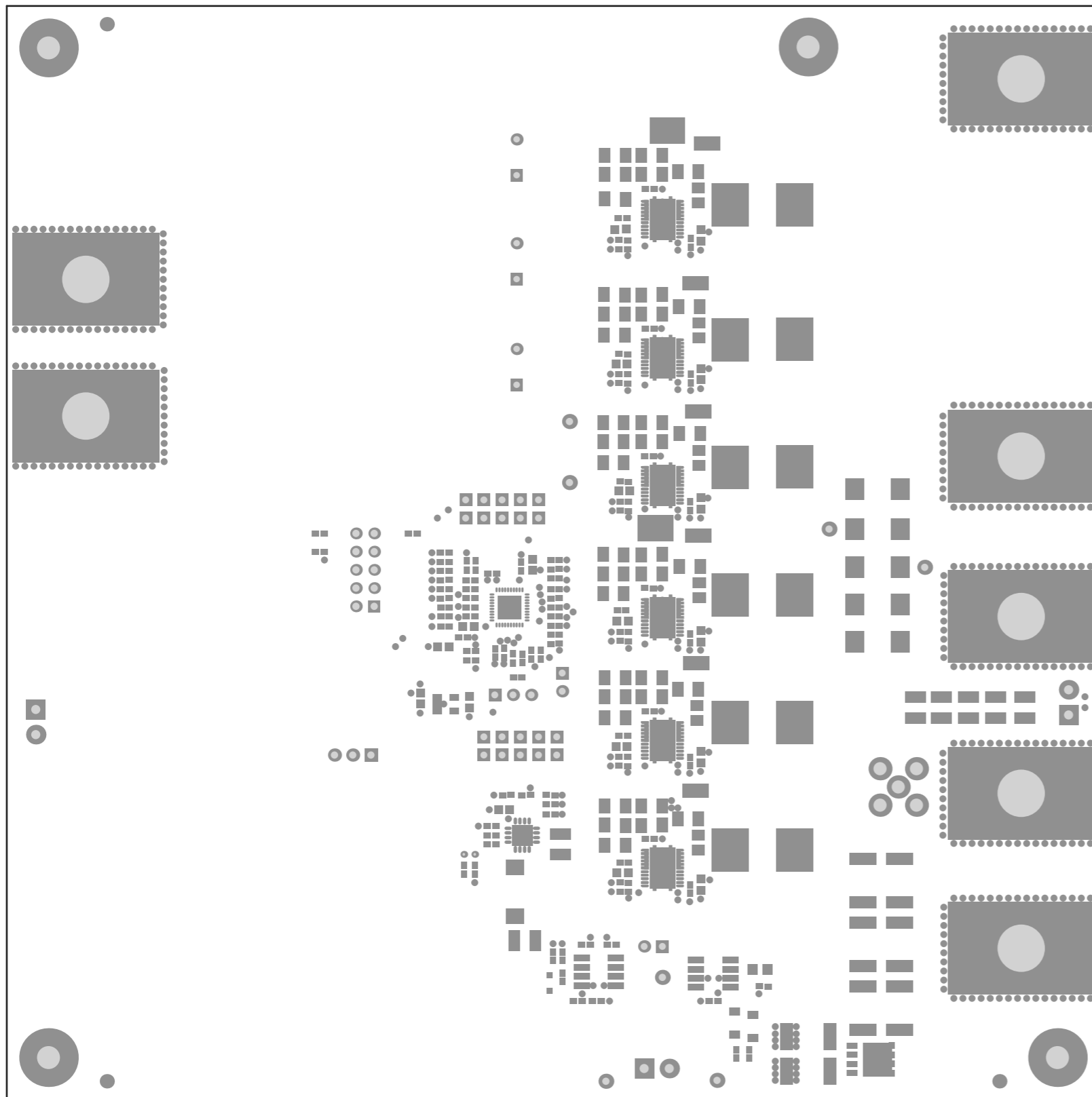
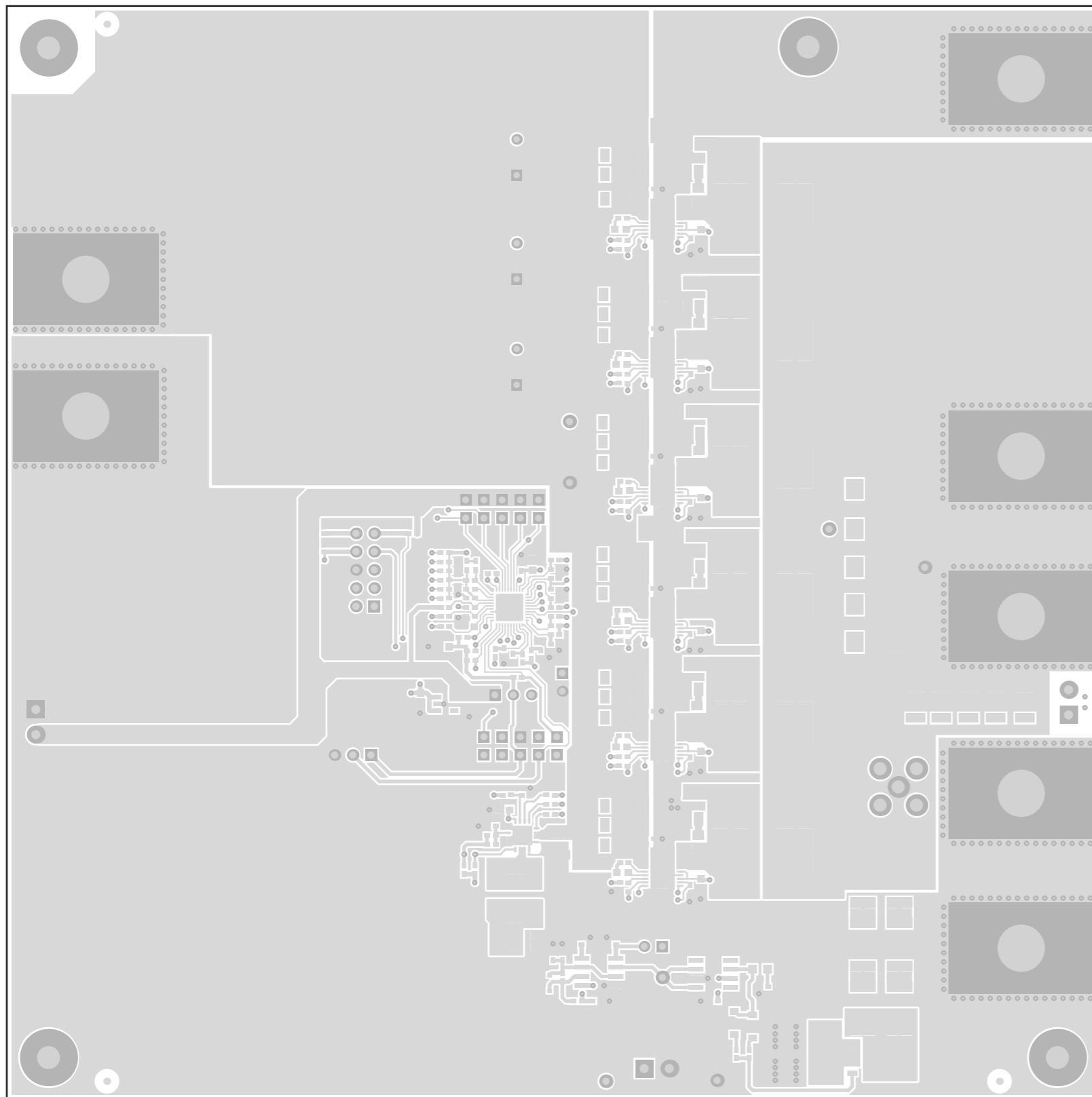


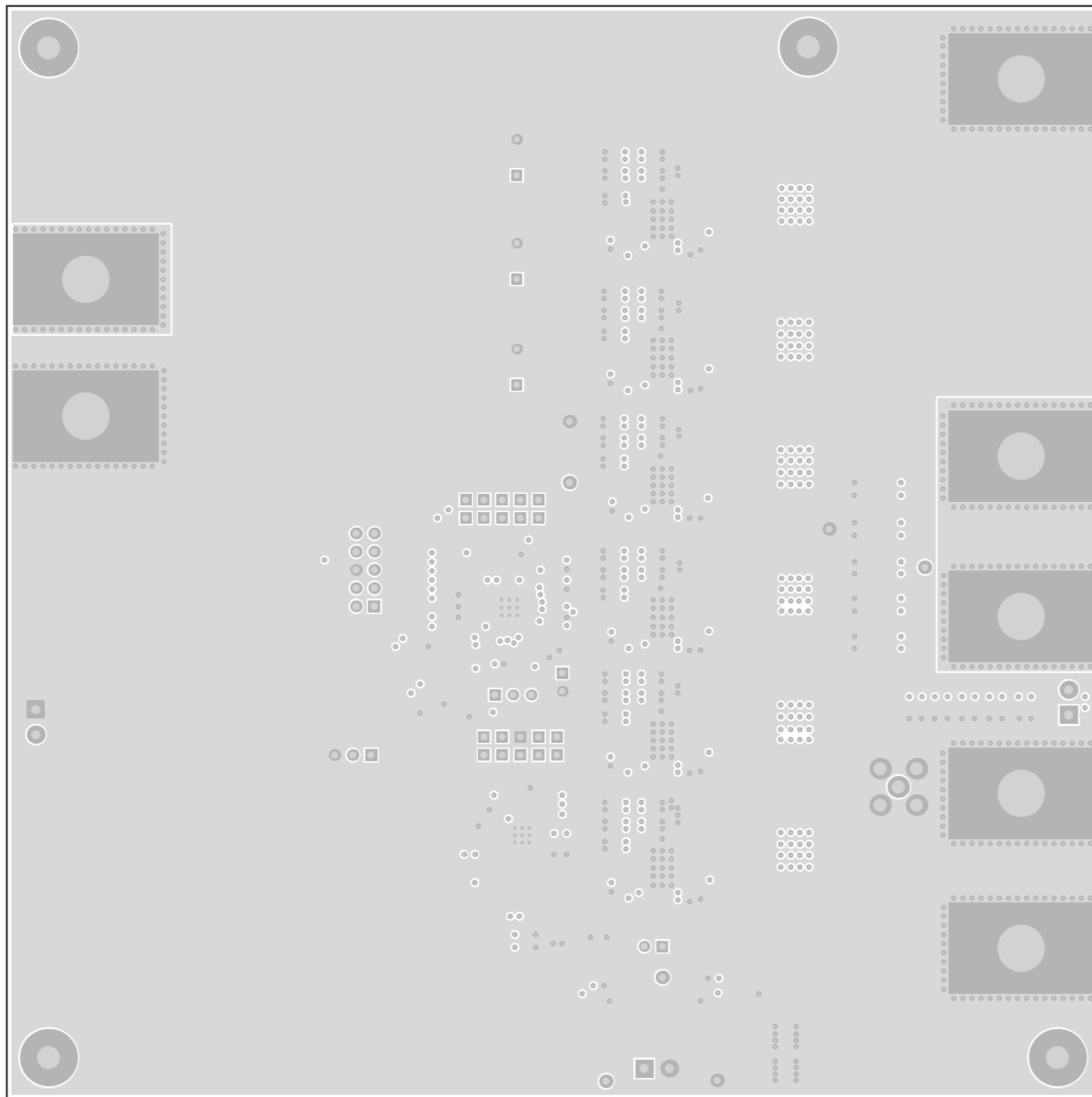
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 6/3/2014 2:03:13 PM	TEXAS INSTRUMENTS	



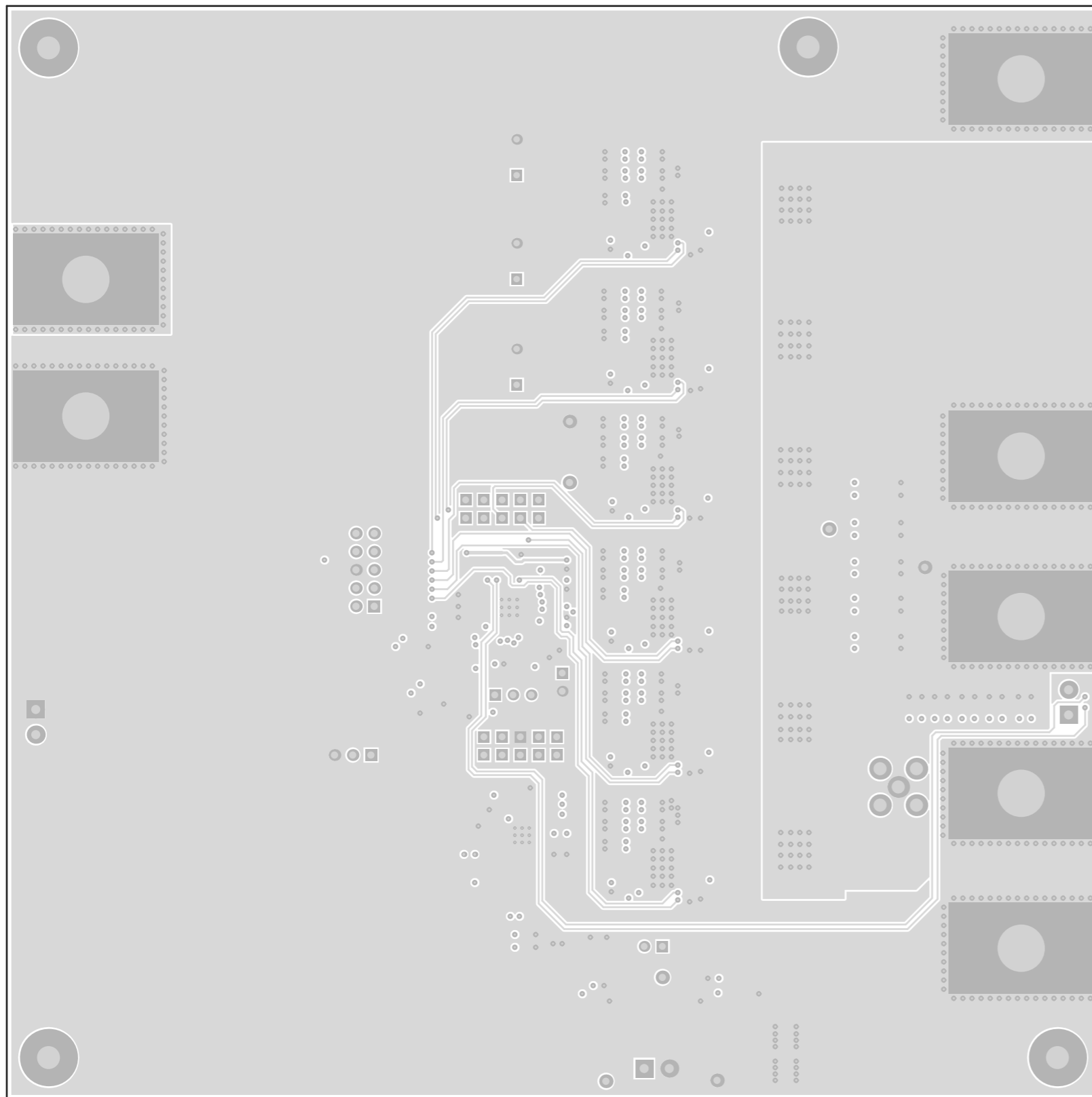
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 6/3/2014 2:03:14 PM	TEXAS INSTRUMENTS	



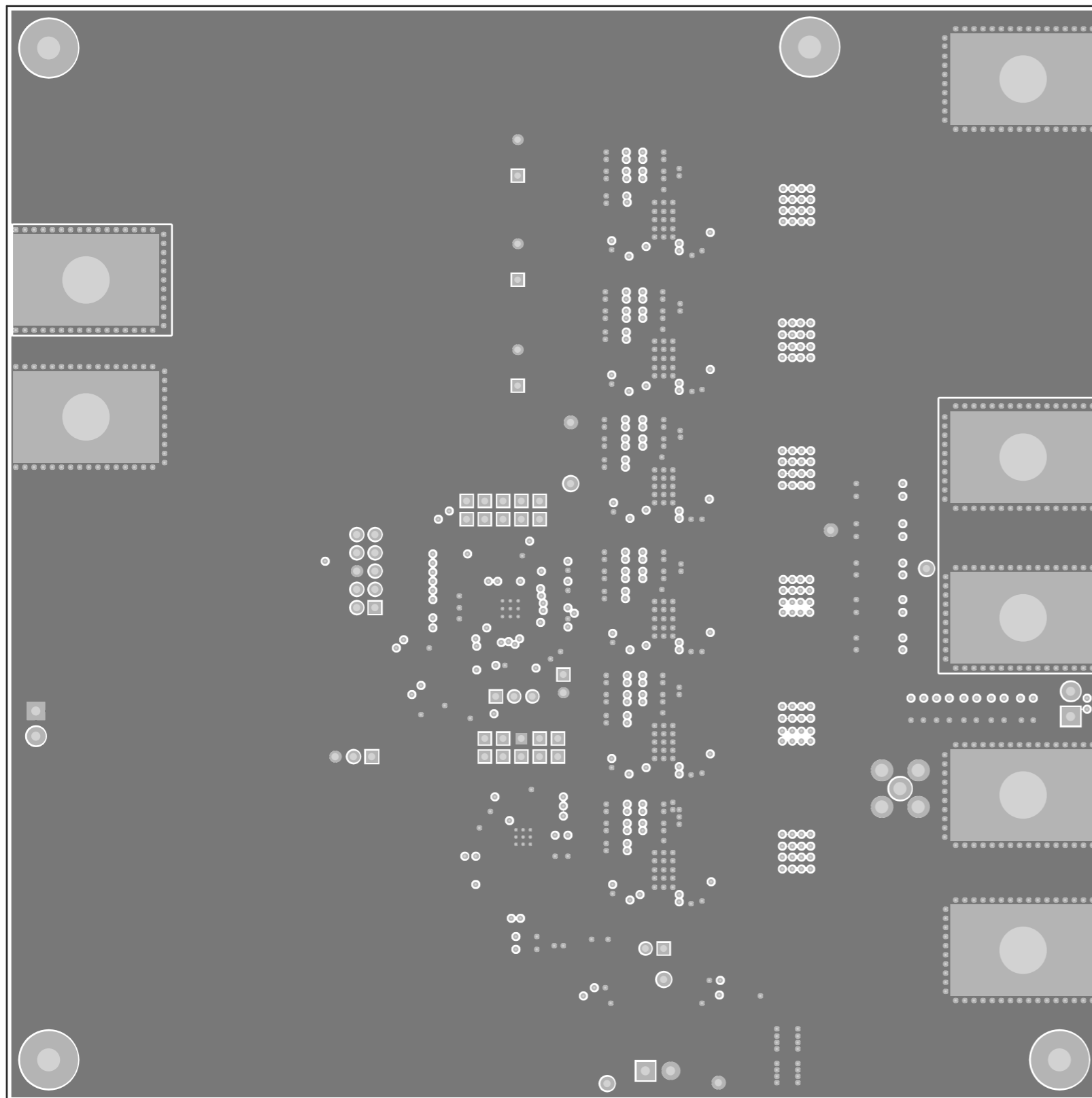
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 6/3/2014 2:03:15 PM	TEXAS INSTRUMENTS	



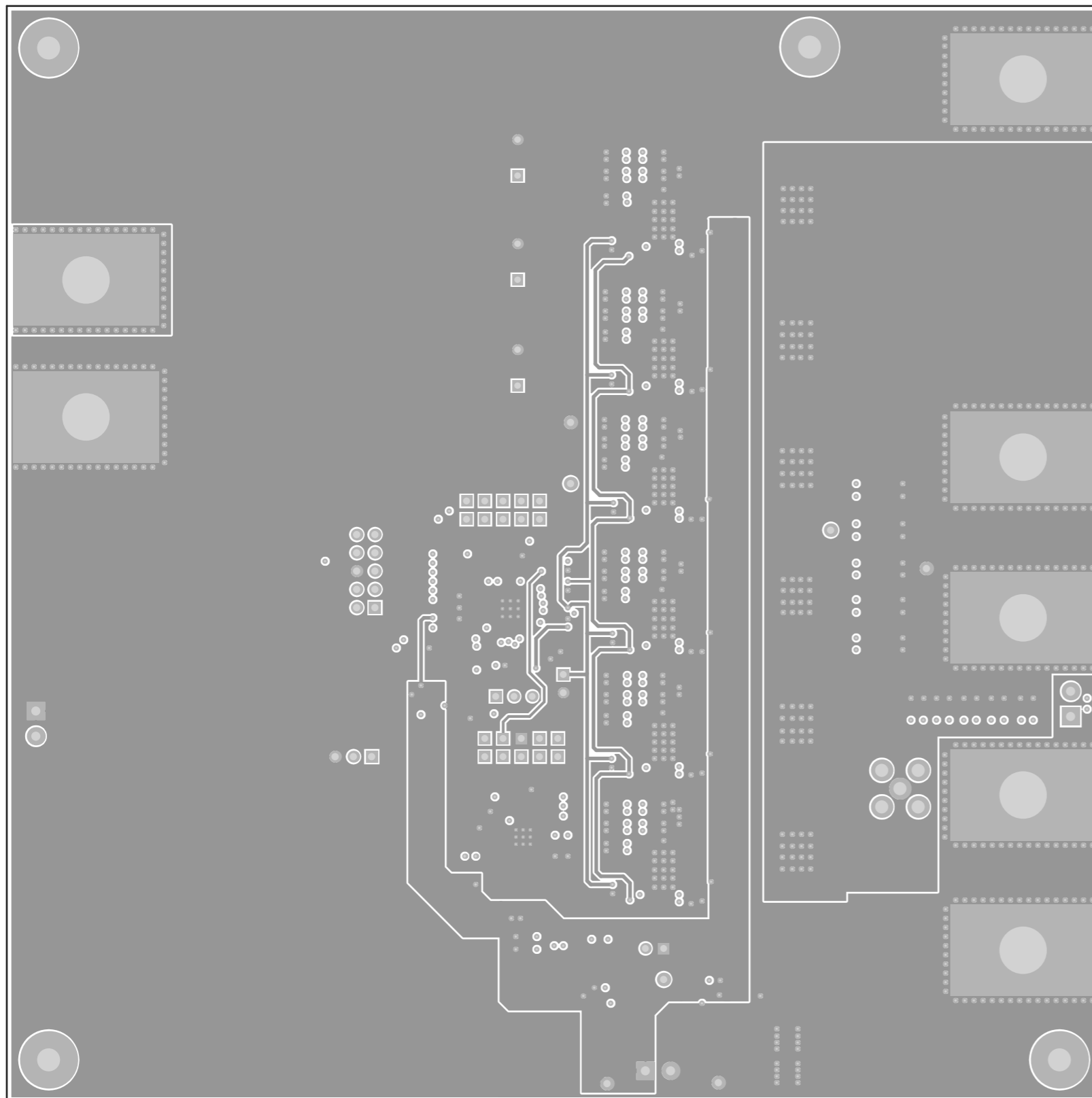
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 6/3/2014 2:03:16 PM	TEXAS INSTRUMENTS	



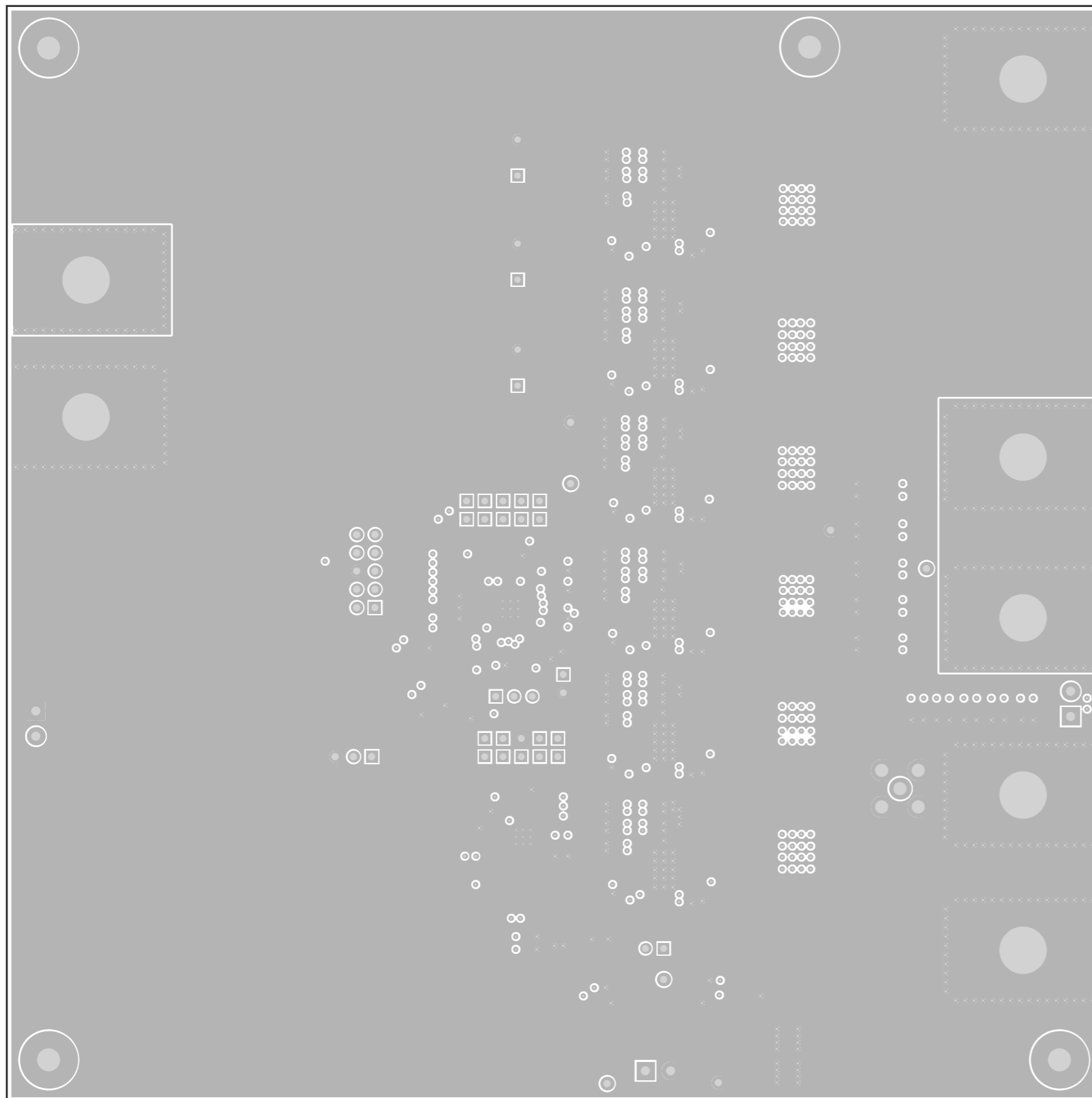
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 6/3/2014 2:03:17 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer3	GENERATED : 6/3/2014 2:03:17 PM	TEXAS INSTRUMENTS	

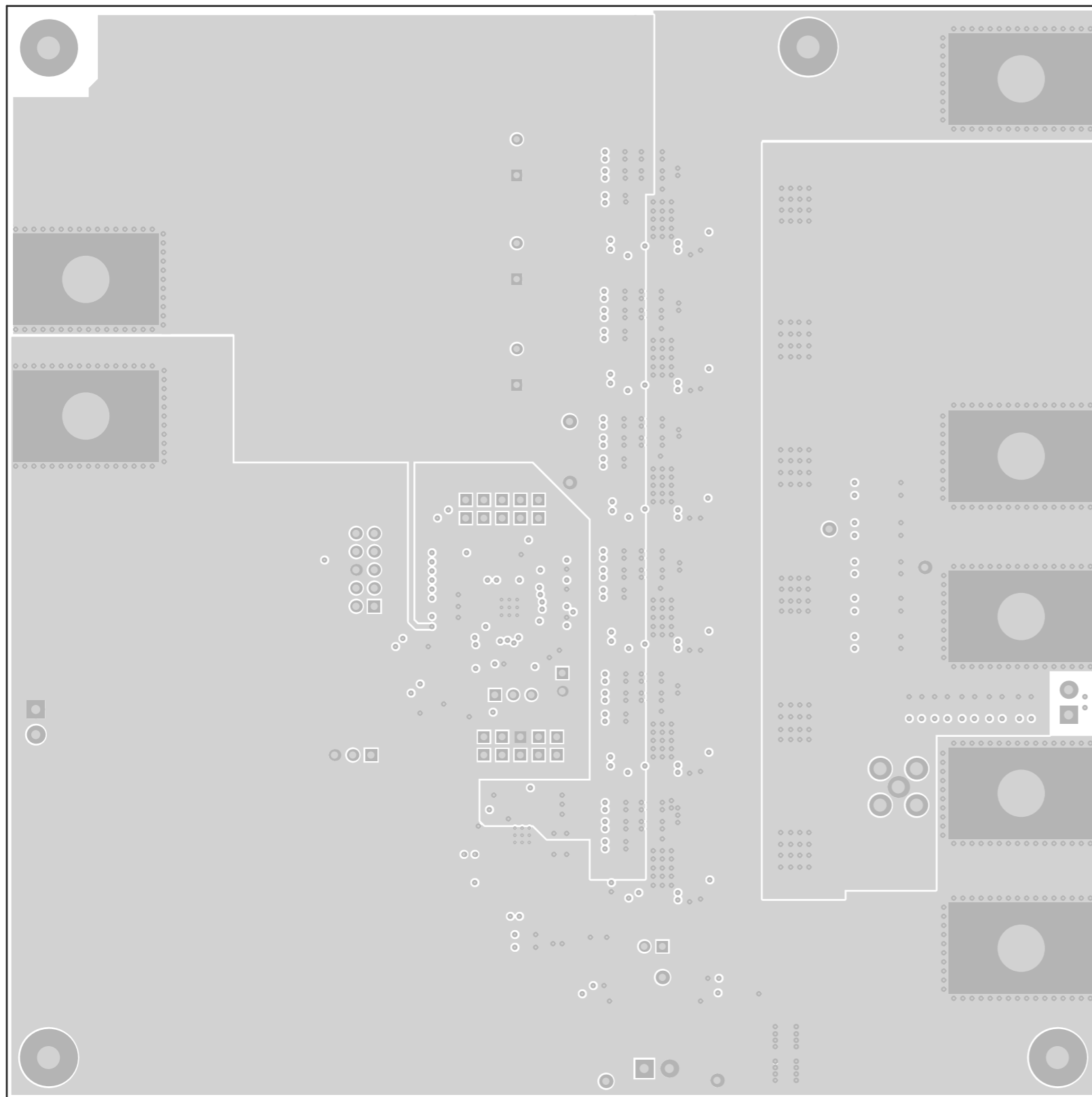


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer 4	GENERATED : 6/3/2014 2:03:18 PM	TEXAS INSTRUMENTS	

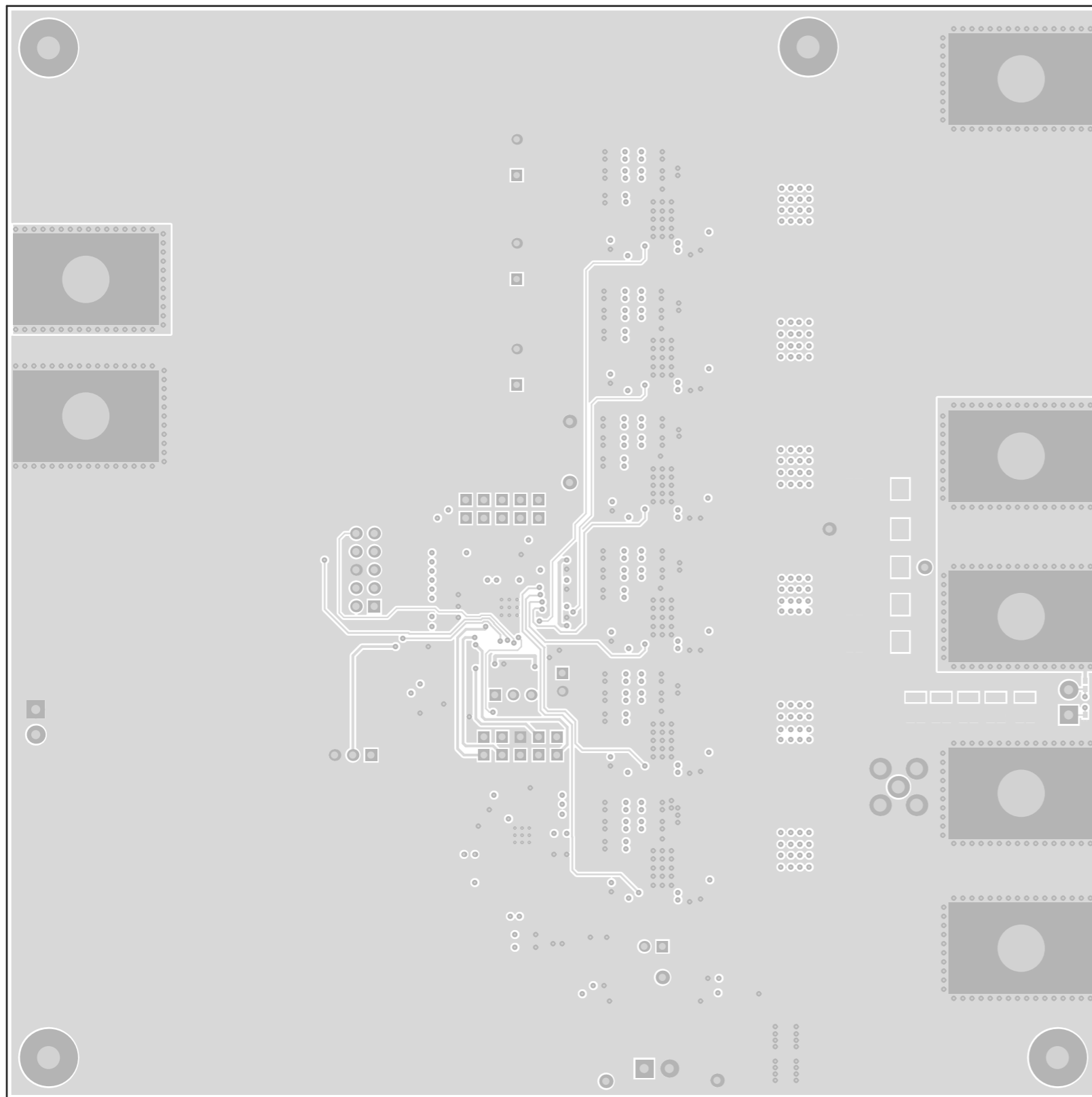


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer5	GENERATED : 6/3/2014 2:03:19 PM	TEXAS INSTRUMENTS	

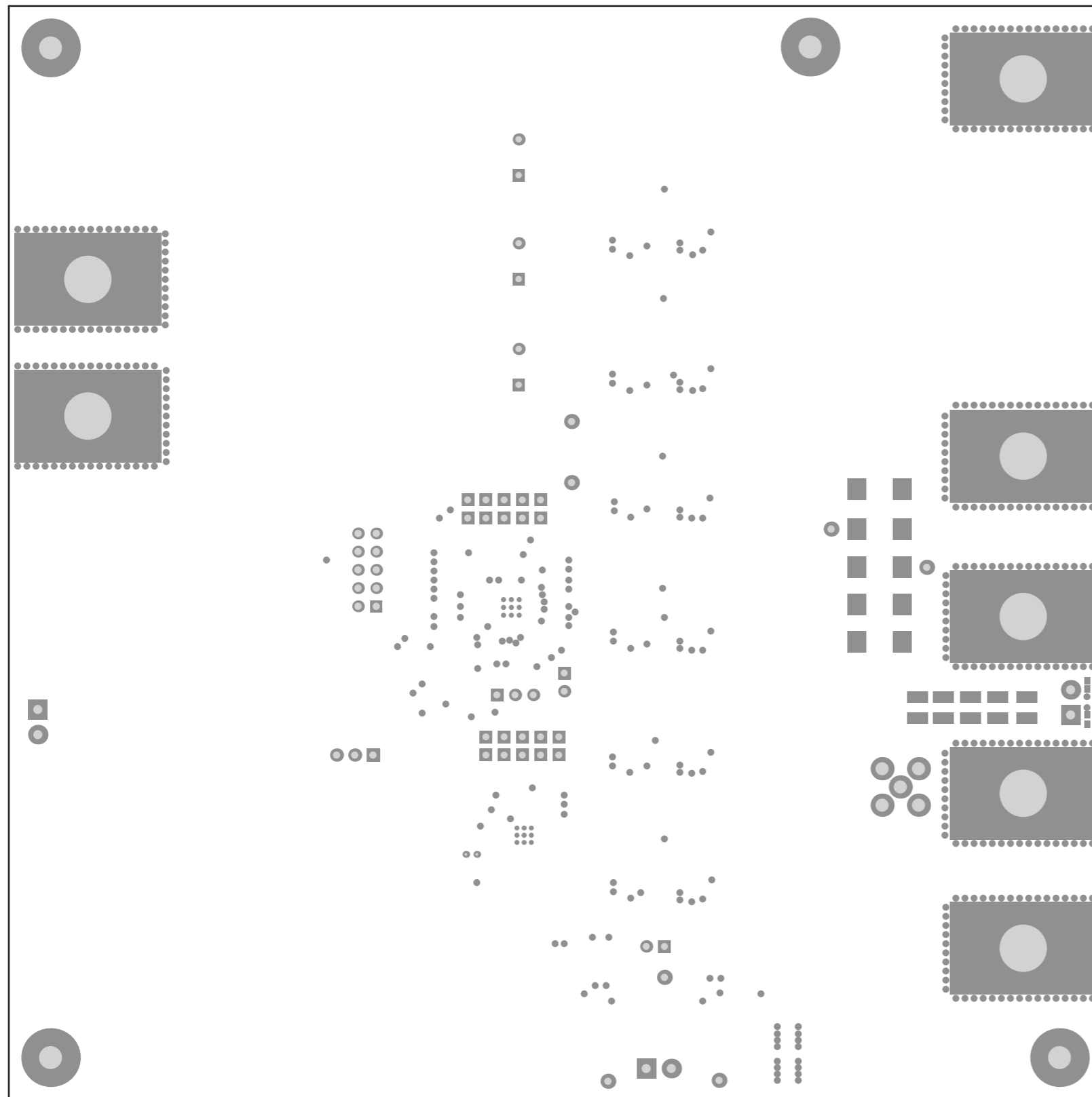




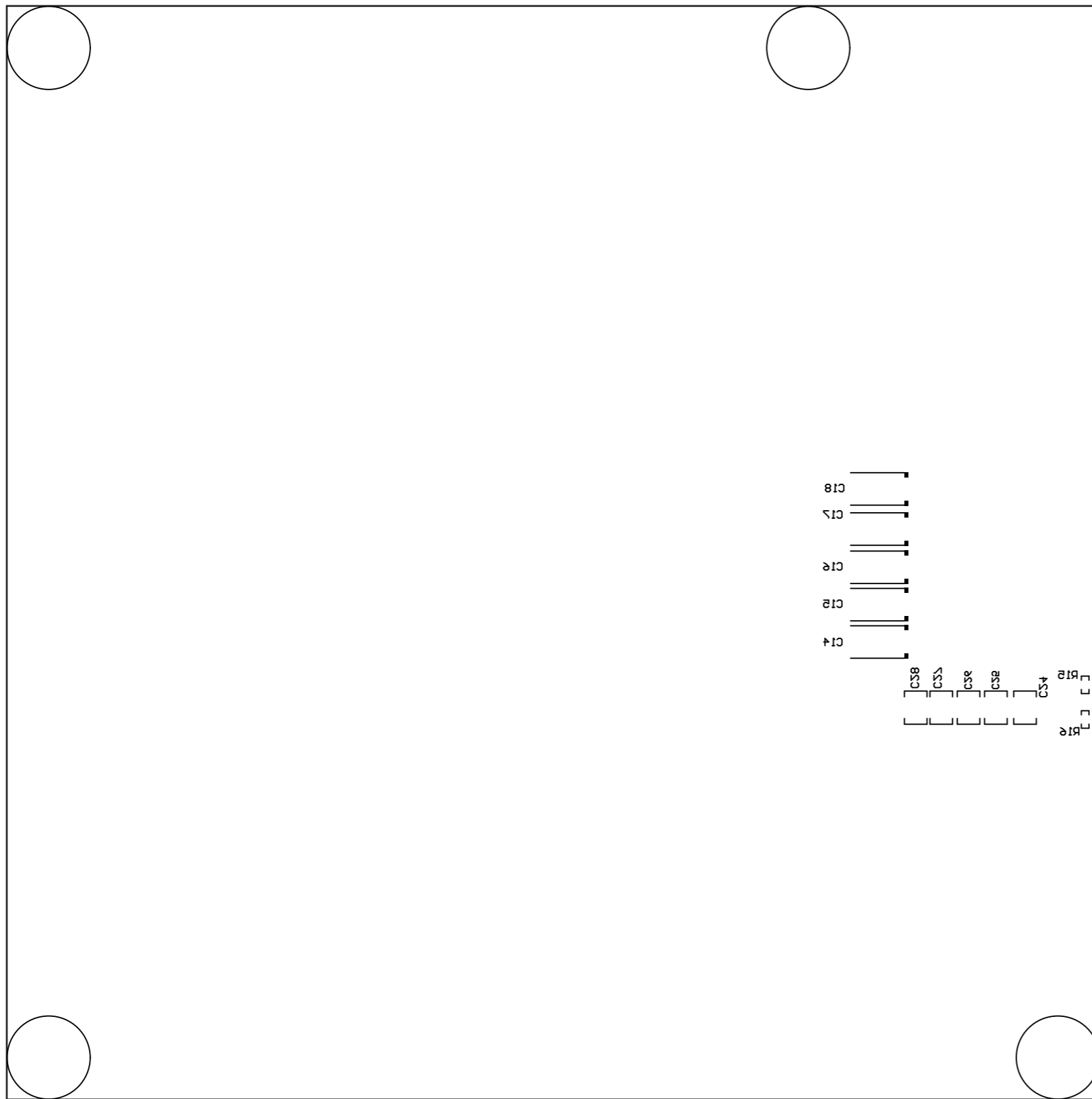
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer6	GENERATED : 6/3/2014 2:03:20 PM	TEXAS INSTRUMENTS	



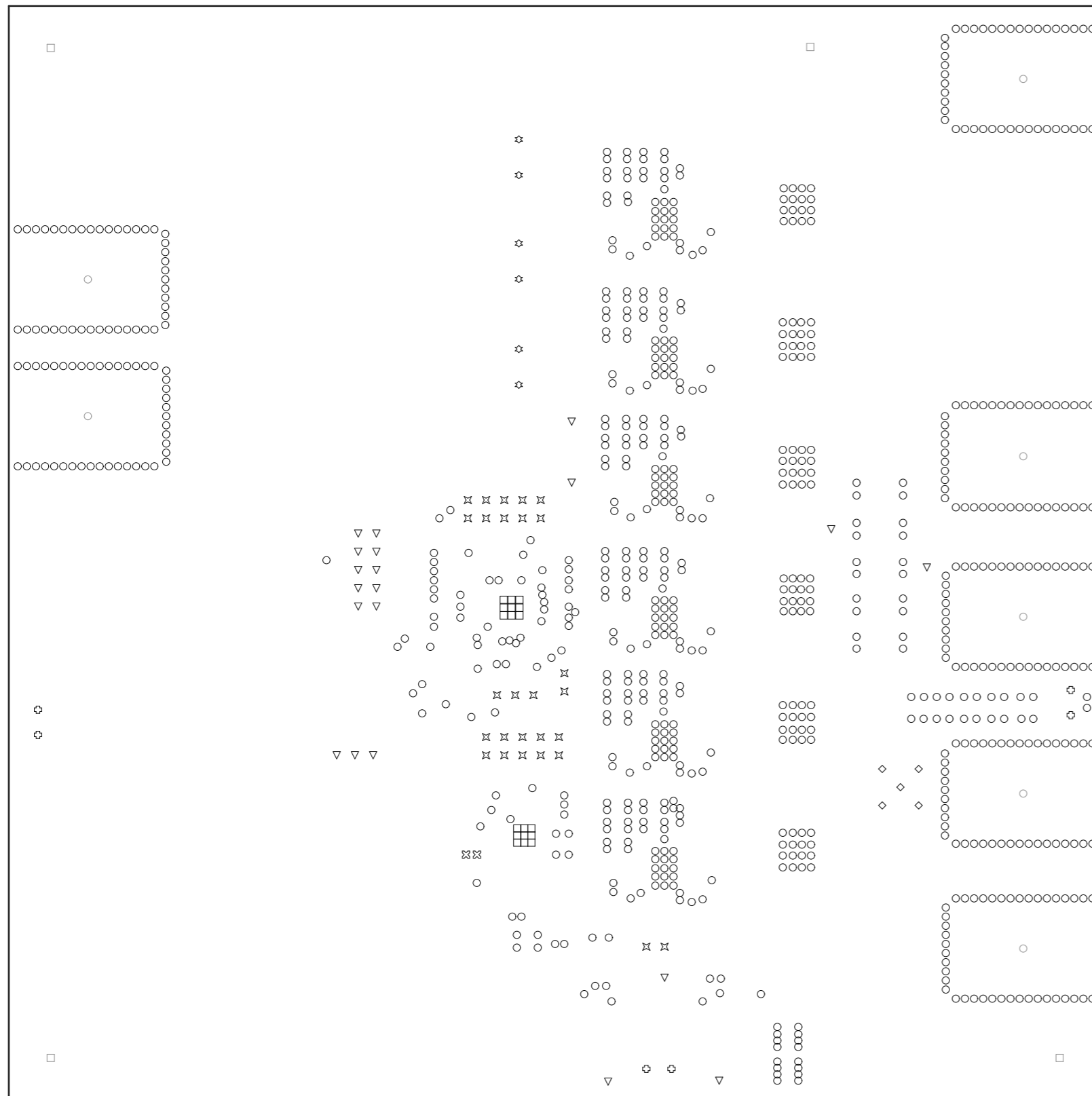
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 6/3/2014 2:03:20 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/3/2014 2:03:21 PM	TEXAS INSTRUMENTS	

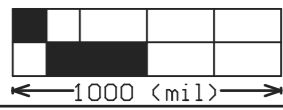
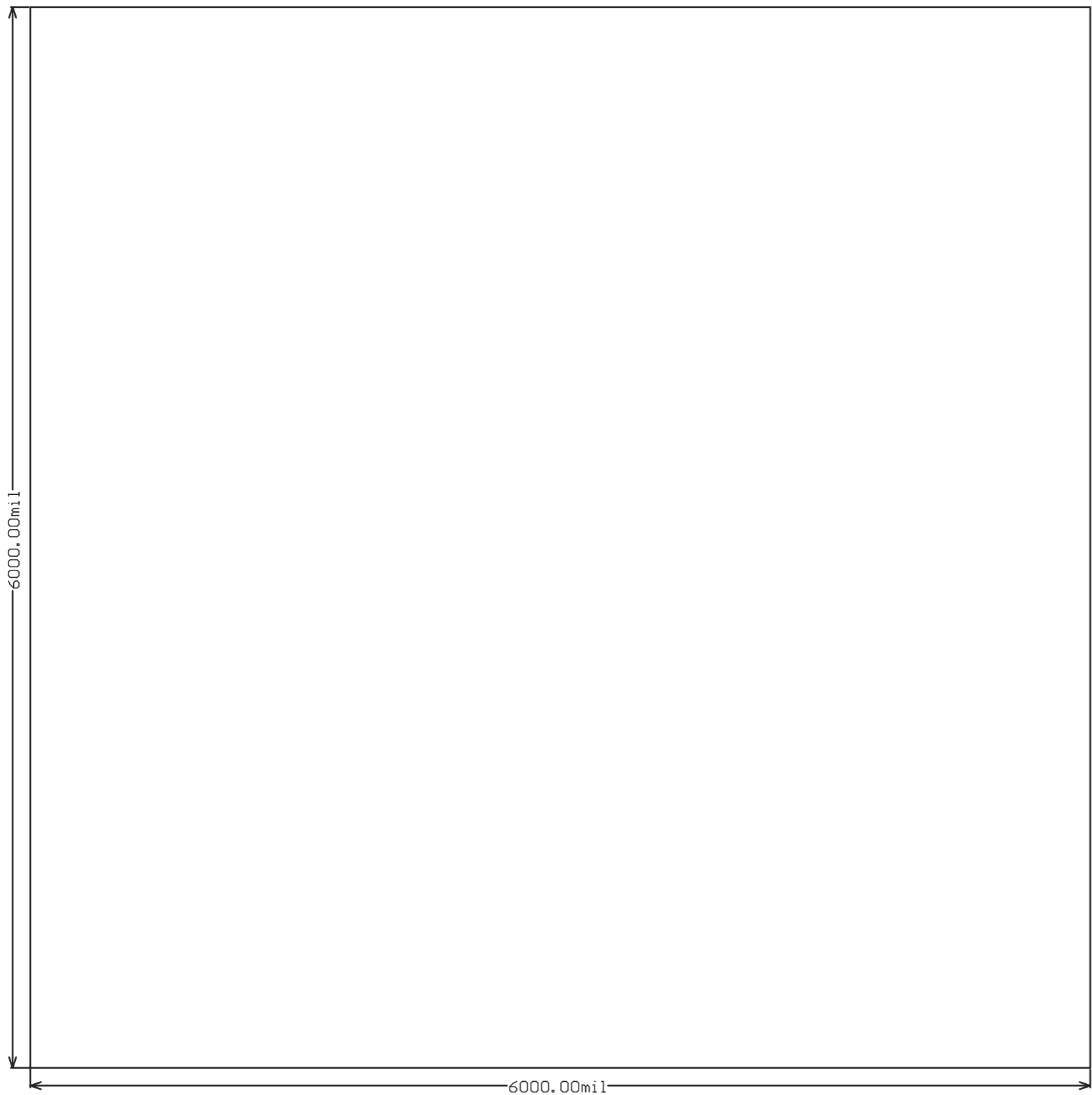


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 6/3/2014	2:03:22 PM	TEXAS INSTRUMENTS



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	18	7.874mil (0.2mm)	PTH	Round
○	823	12mil (0.305mm)	PTH	Round
⊗	2	15mil (0.381mm)	PTH	Round
☆	6	35.433mil (0.9mm)	PTH	Round
✕	27	38mil (0.965mm)	PTH	Round
▽	20	40mil (1.016mm)	PTH	Round
⊕	6	50mil (1.27mm)	PTH	Round
◇	5	73mil (1.854mm)	PTH	Round
⊖	4	125.984mil (3.2mm)	PTH	Round
○	7	260mil (6.604mm)	PTH	Round
<b>918 Total</b>				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 6/3/2014 2:03:23 PM	TEXAS INSTRUMENTS	



1000 (mil)

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9738	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/3/2014 2:03:23 PM	TEXAS INSTRUMENTS	

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